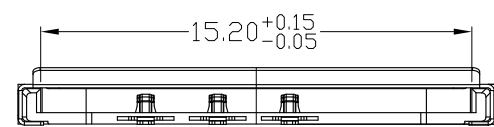
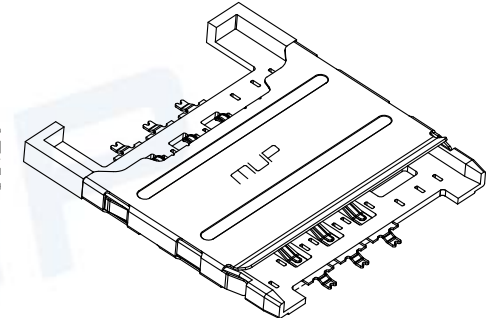
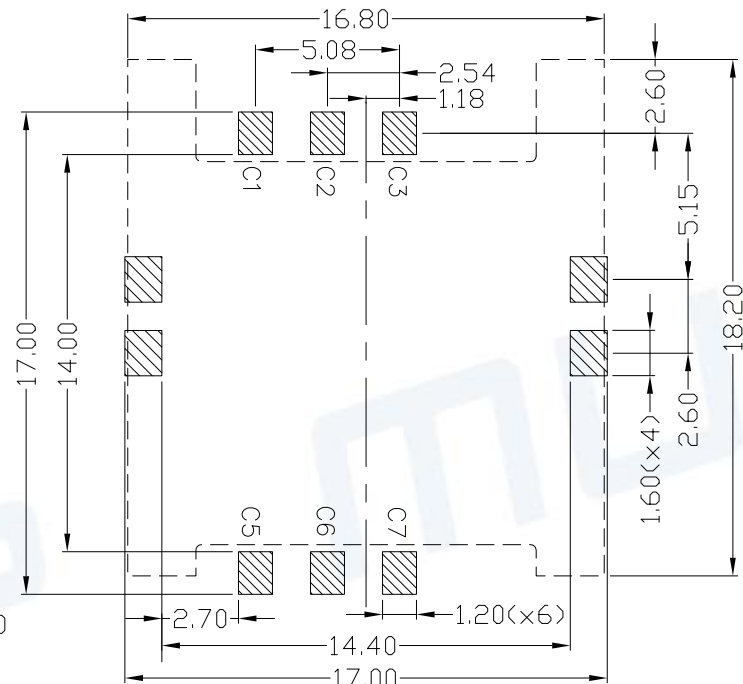
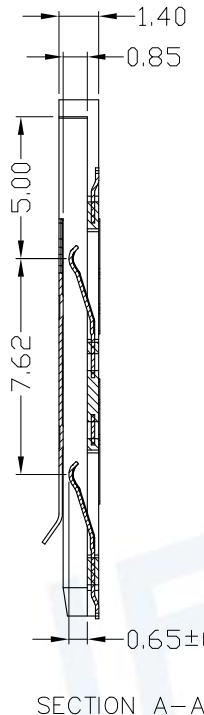
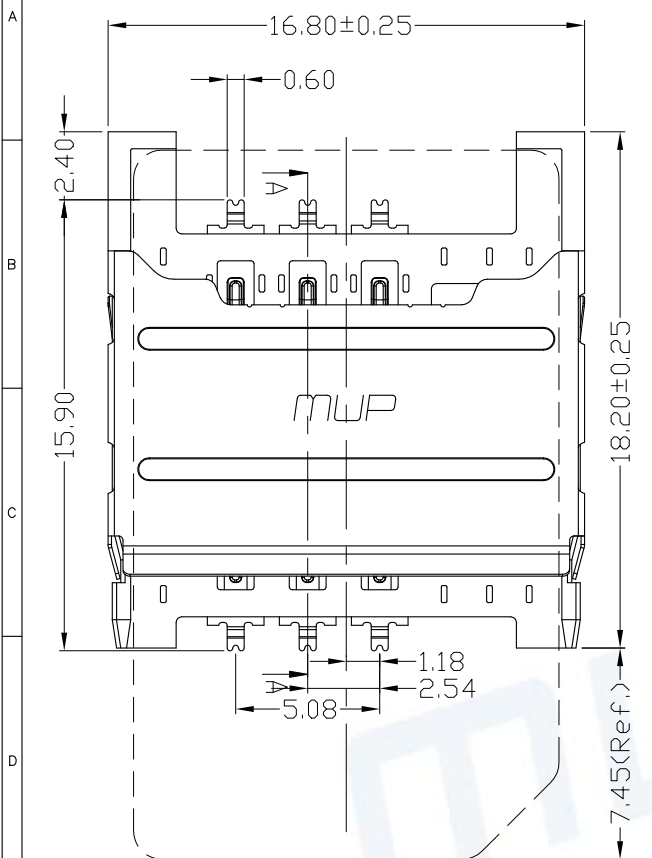


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



0.1Max

**TECHNICAL CHARACTERISTICS**

- General Characteristics**  
 Dimensions: 18.20LX16.80WX1.40H mm  
 Weight: Approx.0.41±0.1g  
 Durability: 5,000 cycles min.
- Electrical Characteristics**  
 Contact resistance: 50mΩ typical, 100mΩ max  
 Insulation resistance: >1000MΩ/500V DC
- Solderability**  
 Vapor phase: 215°C, 30sec. Max  
 IR reflow: 250°C, 5sec. Max  
 Manual soldering: 370°C, 3sec. Max
- Environmental Characteristics**  
 Operating temperature: -40°C~+85°C  
 Operating humidity: 10%~+95%RH



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5*
X.X	±0.25	X.X*	±4*
X.XX	±0.15	X.XX*	±3*
X.XXX	±0.10	X.XXX*	±2*

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**  
 MODEL NO: **MUP C701-2**  
 TYPE: **without post 6pin(shell lengthen)**

PROJ.	UNIT	SCALE	DRAWN	Zoey	Aug.20.2009	DWG NO.:	
	mm	1:1	CHECKED	Jimmy	Aug.20.2009	DWG-MUP-C701-002	
CUSTOMER DRAWING			APPROVAL	Simon	Aug.20.2009	SHEET	REVISION
						1/1	X1